

Intel® Xeon® Processor code-named “Nehalem”



Next-Generation Intel® Core™ Microarchitecture

- Next step in processor energy efficiency, performance, and dynamic scalability

New Platform Architecture

- Optimized for high bandwidth using Intel® QuickPath interconnect and integrated memory controller

Latest Advancements in Technology

- Integrated DDR3 memory controller
- Second-generation PCI Express*
- Intel® Virtualization Technology

Boxed processors and boxed thermal solutions will be sold separately.
Both include 3-year limited warranty.

[www.intel.com/technology/
architecture-silicon/next-gen](http://www.intel.com/technology/architecture-silicon/next-gen)



Thermal Solution Quick Reference

Intel® Thermal Solution STS100 Series for Nehalem-EP Processors in the LGA1366 Socket

Product Name	STS100A	STS100C	STS100P
Boxed Product Code	BXSTS100A	BXSTS100C	BXSTS100P
Maximum CPU TDP	80W	130W	95W
Heat Sink	Active	Combination: Active/ 2U Passive	Passive
Recommended Usage for Heat Sink¹	With fan: <ul style="list-style-type: none">▪ Pedestal chassis with adequate ventilation and correct air temperature	With fan: <ul style="list-style-type: none">▪ Pedestal chassis with adequate ventilation and correct air temperature	
		Without fan: <ul style="list-style-type: none">▪ Pedestal chassis with ducted airflow▪ 2U or larger rack chassis with ducted airflow	Without fan: <ul style="list-style-type: none">▪ 1U or 2U rack chassis with ducted airflow

¹ Contact your chassis supplier for compatibility details.

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*Other names and brands may be claimed as the property of others. 0808/EH/LAI/HP/1K 320443-001

